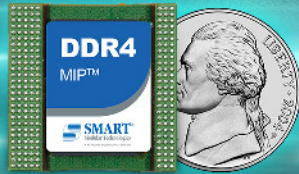
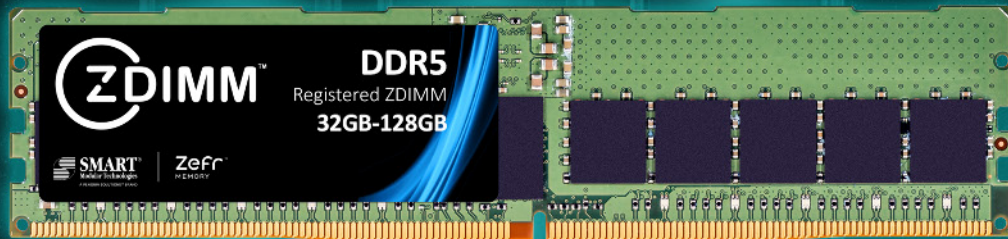




**SMART**<sup>®</sup>  
Modular Technologies

A PENGUIN SOLUTIONS™ BRAND



# Special DIMM Type Product Line

## Introduction

SMART Modular has a long history of successfully partnering with customers to satisfy their specific design needs. With extensive industry and design expertise and global manufacturing capabilities, SMART Modular offers a unique combination of advantages that can support customers' designs from conception to manufacturing through final testing and logistics. This blend of abilities allows SMART Modular to efficiently and reliably customize products to meet particular customer needs.

SMART Modular delivers solutions to a broad customer base, including OEMs in computing, networking, communications, storage, mobile and industrial markets. Available in registered, unbuffered, and ECC configurations, SMART Modular's DRAM memory modules are available in various form factors that include standard height and special DIMM types, including Very Low Profile (VLP), Ultra Low Profile (ULP), mini-DIMM, Module-in-a-Package (MIP), LRDIMM and Zefr ZDIMM.

Among these special DIMM types,

- Small form factor DIMMs are particularly designed and manufactured for space-constrained applications, such as 1U blade servers and blade enclosure systems, to improve airflow inside the system and reduce thermal impact.
- LRDIMMs, with specific configurations intended for servers, workstations and data center applications, allow adding more DIMMs per channel to maximize capacity and performance.
- ZDIMMs (Zefr Memory Module) utilize SMART's Zefr™ proprietary screening process, ensuring the industry's highest levels of uptime and reliability.

## Special DIMM Type Memory Products



VLP + VLP Mini



ULP + ULP Mini



Mini DIMM



MIP



LRDIMM

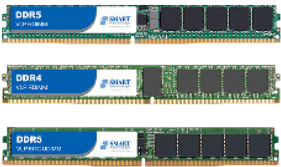


ZDIMM





## VLP DIMM



### Features & Benefits

- DIMM Height of 18.75mm for Vertical Placement in 1U Blades
- Maximize System Density and Performance - up to 384GB in 1U Blade Systems with 12 DIMM Sockets
- Maximize Air Flow in Dense Systems
- Zefr™ High Reliability

### Applications

- Blade Servers – Compute & Storage
- Telecom and Networking ATCA Blades
- Embedded & Edge Computing

### Use Case



| DIMM Type              | VLP RDIMM |            | VLP ECC UDIMM |
|------------------------|-----------|------------|---------------|
| Module Type            | DDR5      | DDR4       | DDR5          |
| Density                | 32GB      | 4GB - 64GB | 16GB - 64GB   |
| Height                 | 18.75 mm  | 18.75 mm   | 18.75 mm      |
| Configuration          | 80bit     | 72bit      | 72bit         |
| Speed (MT/s)           | 4800-5600 | 2666-3200  | 4800-5600     |
| Voltage                | 1.1V      | 1.2V       | 1.1V          |
| Operating Temperature* | C Temp    | C Temp     | C/I Temp      |

\*C Temp (0 °C to +70 °C); I Temp (-40 °C to +85 °C)

## VLP Mini DIMM



### Features & Benefits

- DIMM Height of 18.75mm for Vertical Placement in 1U Blades
- Maximize System Density and Performance - up to 384GB in 1U Blade Systems with 12 DIMM Sockets
- Maximize Air Flow in Dense Systems
- Zefr™ High Reliability

### Applications

- Blade Servers – Compute & Storage
- Telecom and Networking ATCA Blades
- Embedded & Edge Computing

### Use Case



| DIMM Type              | VLP Mini UDIMM | VLP Mini RDIMM |
|------------------------|----------------|----------------|
| Module Type            | DDR4           | DDR4           |
| Density                | 4GB            | 8GB - 16GB     |
| Height                 | 18.75 mm       | 18.75 mm       |
| Configuration          | 72bit          | 72bit          |
| Speed (MT/s)           | 3200           | 3200           |
| Voltage                | 1.2V           | 1.2V           |
| Operating Temperature* | C Temp         | C Temp         |

\*C Temp (0 °C to +70 °C); I Temp (-40 °C to +85 °C)



## ULP DIMM



### Features & Benefits

- Suitable for Space-constrained Blade Applications
- For Vertical Placement in 1U Blades
- Maximize System Density and Performance
- Built-in ECC to Detect and Correct Memory Errors

### Applications

- Blade Servers – Compute & Storage
- Telecom and Networking ATCA Blades
- Embedded & Edge Computing

### Use Case



| DIMM Type              | ULP ECC UDIMM |
|------------------------|---------------|
| Module Type            | DDR4          |
| Density                | 16GB - 32GB   |
| Height                 | 17.78 mm      |
| Configuration          | 72bit         |
| Speed (MT/s)           | 3200          |
| Voltage                | 1.2V          |
| Operating Temperature* | C/I Temp      |

\*C Temp (0 °C to +70 °C)

## ULP Mini DIMM



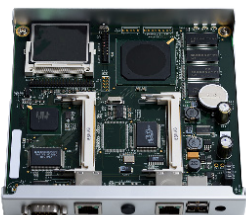
### Features & Benefits

- Suitable for Space-constrained Blade Applications
- For Vertical Placement in 1U Blades
- Maximize System Density and Performance
- Built-in ECC to Detect and Correct Memory Errors

### Applications

- Blade Servers – Compute & Storage
- Telecom and Networking ATCA Blades
- Embedded & Edge Computing

### Use Case



| DIMM Type              | ULP Mini RDIMM |
|------------------------|----------------|
| Module Type            | DDR4           |
| Density                | 16GB - 32GB    |
| Height                 | 17.78 mm       |
| Configuration          | 72bit          |
| Speed (MT/s)           | 3200           |
| Voltage                | 1.2V           |
| Operating Temperature* | C Temp         |

\*C Temp (0 °C to +70 °C)



## Mini DIMM



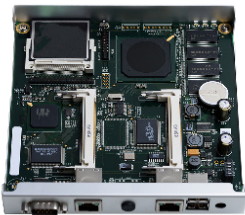
### Features & Benefits

- Command/Address and Control bus is Double Data Rate
- Generates CRC Checksum in READ Data Frames
- Default Burst Length Increased to BL16 – Single Burst = 64B of Data
- Integrated Temperature Sensor (MR4)
- DDR5 DRAM Contains 256 Mode Registers

### Applications

- Networking
- Telecom
- Industrial SBC Blades

### Use Case



| DIMM Type              | Mini RDIMM | ECC Mini UDIMM |
|------------------------|------------|----------------|
| Module Type            | DDR4       | DDR3           |
| Density                | 8GB - 16GB | 8GB            |
| Height                 | 30.00 mm   | 30.00 mm       |
| Configuration          | 72bit      | 72bit          |
| Speed (MT/s)           | 2666       | 1600           |
| Voltage                | 1.2V       | 1.35V          |
| Operating Temperature* | C Temp     | C Temp         |

\*C Temp (0 °C to +70 °C)

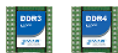
## Module-In-A-Package™ (MIP™)

### Features & Benefits

- Occupies Only 1/5th the Space of an SODIMM
- Up to 42% Power Savings Comparing to SODIMMs
- Superior Ruggedness – Soldered Down; No Sockets or Clips
- Leverages SMART's Proven Stacking Technology

### Applications

- Video Broadcast
- Video/Graphics Cards
- Embedded Computing
- Telecom
- Defense/Aerospace
- Automotive



### Use Case



| DIMM Type              | Module-In-A-Package (MIP) |                         |
|------------------------|---------------------------|-------------------------|
| Module Type            | DDR4                      | DDR3                    |
| Density                | 4GB - 16GB                | 2GB                     |
| Height                 | 22.25 x 22.25 x 3.85 mm   | 22.25 x 22.25 x 3.85 mm |
| Configuration          | 64bit                     | 64bit                   |
| Speed (MT/s)           | 3200                      | 1866                    |
| Voltage                | 1.2V                      | 1.35V                   |
| Operating Temperature* | C/I Temp                  | C Temp                  |

\*C Temp (0 °C to +70 °C); I Temp (-40 °C to +85 °C)





# LRDIMM



## Features & Benefits

- Load-Reduced Dual In-Line Memory Modular (LRDIMM)
- JEDEC Standard
- Three DIMM per Channel Server Configurations
- High Speed Data Rates
- Minimize Supply Chain Disruptions by Self-Qualifying New Die Revs and Providing Multi-sourced DRAM Options

## Applications

- Data Centers Requiring Large Amounts of Server Memory
- Enterprise Grade LRDIMMs Available for Mission Critical Applications

## Use Case

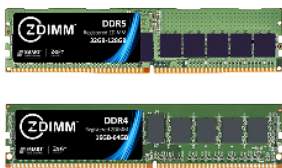


| DIMM Type              | LRDIMM   |
|------------------------|----------|
| Module Type            | DDR4     |
| Density                | 32GB     |
| Height                 | 31.25 mm |
| Configuration          | 72bit    |
| Speed (MT/s)           | 2666     |
| Voltage                | 1.2V     |
| Operating Temperature* | C Temp   |

\*C Temp (0 °C to +70 °C)



# Zefr ZDIMM



## Features & Benefits

- Five Testing Process: Temperature, Speed, Load, System & Time
- Zefr Testing Emulates the Most Strenuous Use Cases Producing
- Proven Long-Term Reliability with 200 or Less DPPM (vs. Industry Standard of 3,000-5,000 DPPM)
- Available in DDR4 and DDR5

## Applications

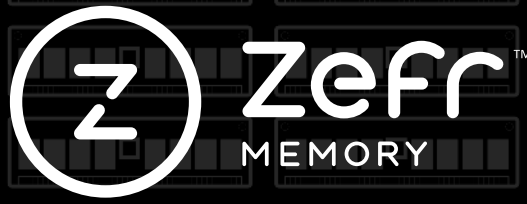
- Natural Language Processing (LLMs)
- Image Recognition, 3D Rendering, Security Camera Data Processing
- DNA Sequencing, High Resolution Medical Image Processing
- Algorithmic Trading, Real Time High-Speed Analytics

## Use Case



| DIMM Type              | Zefr ZDIMM   |             |
|------------------------|--------------|-------------|
| Module Type            | DDR5         | DDR4        |
| Density                | 32GB - 128GB | 16GB - 64GB |
| Height                 | 31.25 mm     | 31.25 mm    |
| Configuration          | 80bit        | 72bit       |
| Speed (MT/s)           | 5600         | 3200        |
| Voltage                | 1.1V         | 1.2V        |
| Operating Temperature* | C Temp       | C Temp      |

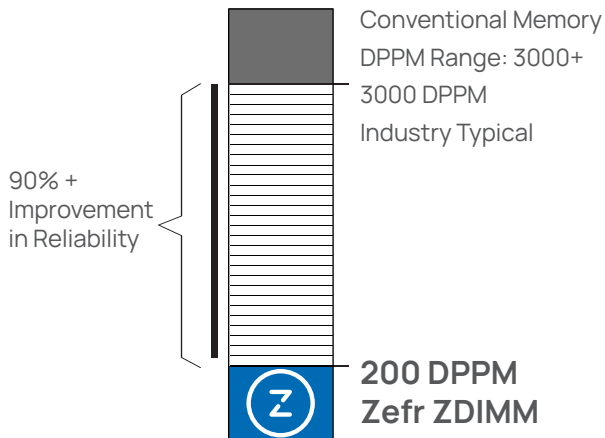
\*C Temp (0 °C to +70 °C)



# Ultra-High Reliability Zefr™ ZDIMM Memory

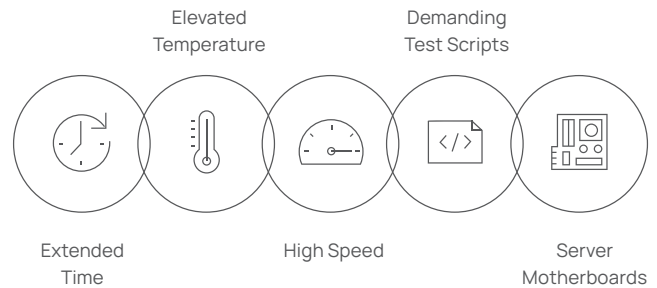
Eliminate over **90%** of Memory Reliability Failures

## Industry Standard Memory Reliability isn't Sufficient



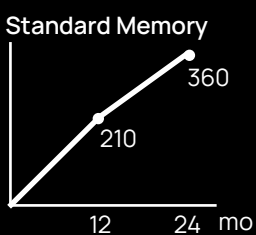
## Zefr Screens Memory to Real-World Conditions

Zefr ZDIMM has been intensely processed to filter out weak memory modules. The Zefr Process combines five key testing ingredients.



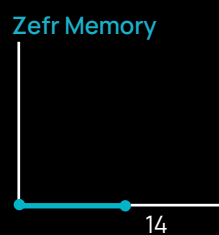
## Case Study

An HPC System Integrator built identical systems with standard and Zefr memory.



Purchase 18,384 Standard RDIMMs  
Build Cluster A:  
• 1,532 Nodes  
• Twelve 16GB RDIMMs per Node

Field Failures since Platform Bring up:  
360 Failures



1Purchase 18,384 Standard RDIMMs  
Build Cluster B:  
• 1,532 Nodes  
• Twelve 16GB RDIMMs per Node

Field Failures since Platform Bring up:  
**0** Failures



# Think Memory. Think SMART.

For more product details, please contact the SMART sales team or visit our website.

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